

## **Device Material Content**

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Package: Total Device Weight 1152 fpBGA 5.50 Grams with SnAgCu Solder Balls

**Copper Bond Wire version** 

MSL: 3 Peak Reflow Temp: 250°C

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December, 2012	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS#	Notes / Assumptions:
Die	4.04%	0.2223			Silicon chip	7440-21-3	Die size: 17.25 x 17.72 mm
Mold	34.46%	1.8951	30.18% 2.41% 1.72% 0.14%	1.6601 0.1327 0.0948 0.0076	Silica Fused Epoxy Resin Phenol Resin Carbon Black	60676-86-0 Trade secret Trade secret 1333-86-4	Mold Compound composition: 75 to 95% Silica (LSC uses 87.6% in our calculation) 5 to 10% Epoxy Resin (LSC uses 7% in our calculation) 3 to 8% Phenol Resin (LSC uses 5% in our calculation) 0.1 to 0.5% Carbon Black (LSC uses 0.4% in our calculation) Mold Compound Density ranges between 1.95 and 2.05 grams/cc
D/A Epoxy	0.57%	0.0313	0.45% 0.11%	0.0250 0.0063	Silver Organic esters and resins	7440-22-4	Die attach epoxy Density: 4 grams/cc 70 to 90% Silver (LSC uses 80% in our calculation) 10 to 30% Organic Esters and Resins (LSC uses 20% in our calculation)
Wire	0.18%	0.0100	0.98% 0.01%	0.0018 0.0000	Copper Palladium	7440-50-8 7440-05-3	0.8 mil diameter; 1 wire per solder ball 98.5% 1.5%
Solder Balls	20.33%	1.1181	19.62% 0.61% 0.10%	1.0790 0.0335 0.0056	Tin (Sn) Silver (Ag) Copper (Cu)	7440-31-5 7440-22-4 7440-50-8	Qualified Solder ball compositions: Sn96.5/Ag3/Cu0.5
Substrate	19.32%	1.0628	13.14% 6.18%	0.7227 0.3401	Glass fiber BT Resins	65997-17-3	60 to 75% glass fiber (LSC uses 68% in our calculation)
Foil	21.10%	1.1604			Copper (Cu)	7440-50-8	

Notes

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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Rev. E